









# PRODUCT DATASHEET

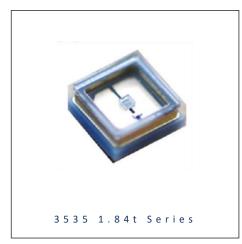




- ► Ceramic High Power
- ➤ 3535 1.84t Series
- ► Ultraviolet UVC (260-280nm)

N0Q52S02Z-260270 N0Q52S02Z-270280





# 3535 1.84t Series





### **FEATURES:**

• Package: Ceramic SMT Package with Glass Lens

Forward Current: 100mAForward Voltage (typ.): 6V

Radiant Power (typ.): 12mW@100mA

Colour: Ultraviolet C (UVC)
Peak Wavelength: 260~280nm

• Viewing angle: 120°

Materials:

Die: AlGaN Flip Chip
Resin: Glass (Water Clear)
Operating Temperature: -30~+60°C

• Storage Temperature: -40~+100°C

• Grouping parameters:

Forward Voltage

- Radiant Power

Peak Wavelength

Soldering methods: IR Reflow

• Moisture Sensitive Level: MSL 2 according to J-STD020

Packing: 12mm tape with min.100pcs/reel, ø180mm (7")

### **APPLICATIONS:**

- Sterilization
- Air Purifier
- Blood Detector
- Skin Therapy
- Dermatology
- Water Purifier
- Disinfection







### **CHARACTERISTICS:**

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	IF	150	mA
Power Dissipation	P <sub>D</sub>	1.1	W
Junction Temperature	Tj	85	°C
Thermal Resistance	R <sub>th</sub>	17	°C/W
Operating Temperature	T <sub>OPR</sub>	-30~+60	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

## Electrical & Optical Characteristics (Ta=25°C)

Parameter Symbol		Values		Unit	Test	
raiailletei	Зуппоот	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	VF	5.0	6.0	7.0	V	I <sub>F</sub> =100mA
Radiant Power	Po	5	9	15	mW	I <sub>F</sub> =100mA
Peak Wavelength	$\lambda_{D}$	260	270	280	nm	I <sub>F</sub> =100mA
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =100mA

<sup>1.</sup> Radiant power ( $\Phi_V$ )  $\pm 7\%$ , Forward Voltage ( $V_F$ )  $\pm 0.05V$ , Viewing angle( $2\theta_{1/2}$ )  $\pm 10^\circ$ , Peak wavelength ( $\lambda_D$ )  $\pm 1$ nm.

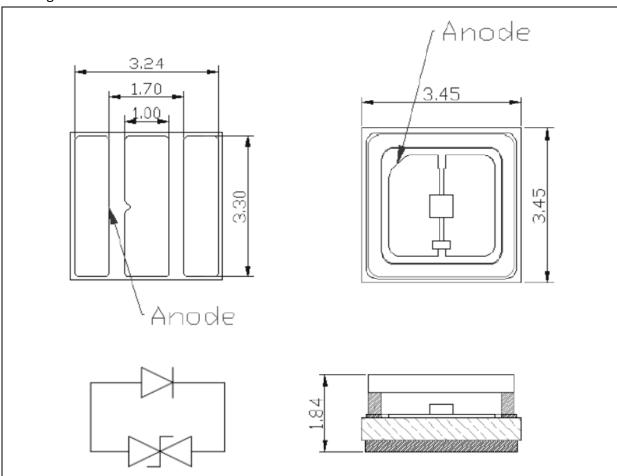






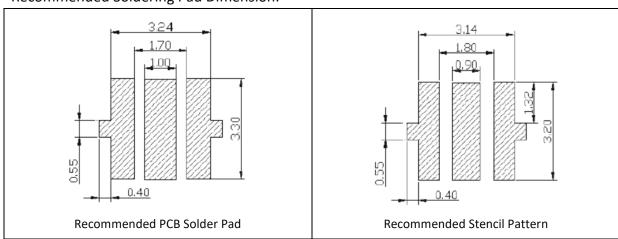
### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

### **Recommended Soldering Pad Dimension:**



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.12mm with angle tolerance ±0.5°.







### **BINNING GROUPS:**

## Forward Voltage Classifications (I<sub>F</sub> = 100mA):

Code	Min.	Max.	Unit
JD	5.2	5.6	
JE	5.6	6.0	V
JF	6.0	6.4	V
JG	6.4	6.8	

### Radiant Power Classifications ( $I_F = 100 \text{mA}$ ):

Code	Min.	Max.	Unit
X02	5	10	
X03	10	15	mW

## Peak Wavelength Classifications (IF = 100mA):

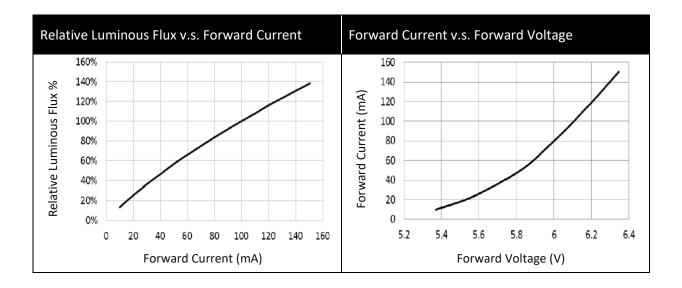
Code	Min.	Max.	Unit
265	260	270	
275	270	280	nm

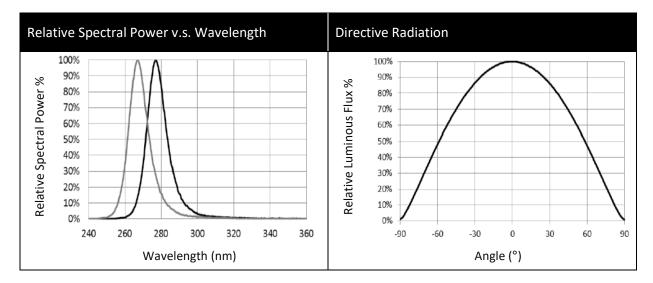






### **ELECTRO-OPTICAL CHARACTERISTICS:**











## **Reliability Tests:**

Test Item	Test Condition	Test Period	Ac/Re
Room Temperature Operating Life (RTOL)	I <sub>F</sub> =100mA DC	1000hrs	0/1
Wet High Temperature Operating Life (WHTOL)	T <sub>A</sub> =60°C; 90% Humidity; I <sub>F</sub> =100mA DC	1000hrs	0/1
Thermal Cycle	-40°C 30mins +125°C 30mins	1000 cycle	0/1
Reflow Soldering	T <sub>max</sub> .=260°C	3 times	0/1

### Notes:

- No catastrophic (LED Fail)
- Radiant flux maintenance > 50%
- Change in VF < 10%
- No corrosion
- Moisture Sensitivity Level 2 (IPC/JEDEC J-STD-020)

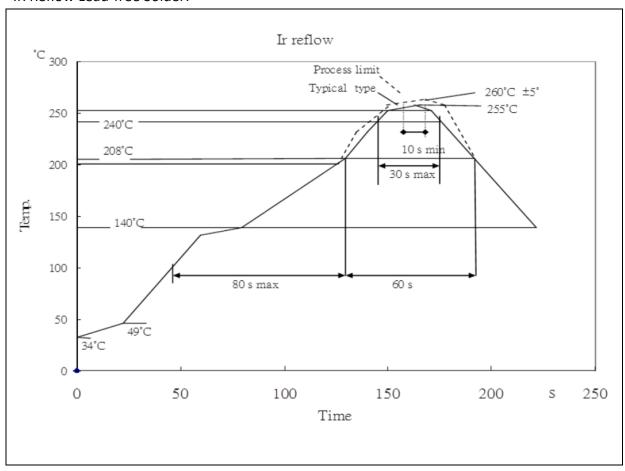






### **RECOMMENDED SOLDERING PROFILE:**

### IR Reflow Lead-free Solder:



### Note:

- 1. Recommend reflow temperature 240 °C. The maximum soldering temperature should be limited to 260 °C.
- 2. Maximum reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.

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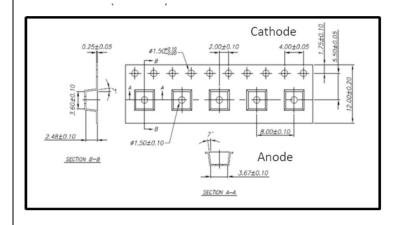




### **PACKING SPECIFICATION:**

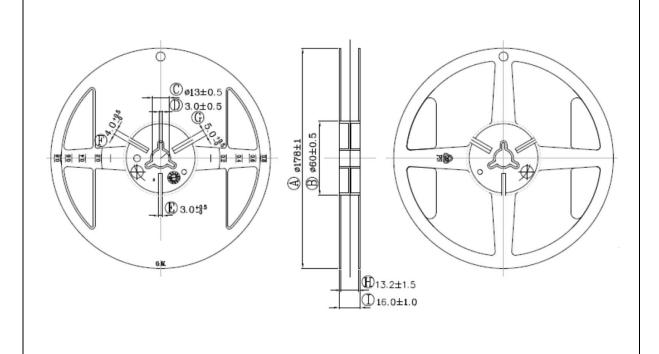
### Reel Dimension:





Item	Specification	Tol.(+/-)
W	12.00	±0.20
Е	1.75	±0.10
F	5.50	±0.05
D0	1.50	+0.10,-0
D1	1.50	±0.10
P0	4.00	±0.05
P1	8.00	±0.10
P1	2.00	±0.10
P0 x 10	40.00	±0.20

t	0.25	±0.05
Α0	3.67	±0.10
В0	3.60	±0.10
K0	2.48	±0.10









#### PRECAUTIONS OF USE:

### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking.

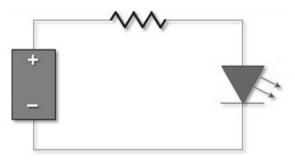
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±3°C x 24hrs and <5%RH, taped / reel package.</li>

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.







### **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	12/09/2020	Datasheet set-up.
A1.1	13/10/2020	Revise product solder pad and height.
A1.2	31/10/2020	Add reliability test items.
A1.3	19/10/2021	Revise voltage and radiant power bin range.